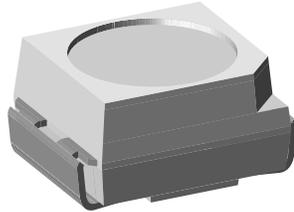




# High Speed Infrared Emitting Diode, 850 nm, Surface Emitter Technology



## LINKS TO ADDITIONAL RESOURCES



## DESCRIPTION

As part of the [SurfLight™](#) portfolio, the VSMY3850X01 is an infrared, 850 nm emitting diode based on surface emitter technology with high radiant intensity, high optical power and high speed, molded in a PLCC-2 package for surface mounting (SMD).

## FEATURES

- Package type: surface-mount
- Package form: PLCC-2
- Dimensions (L x W x H in mm): 3.5 x 2.8 x 1.75
- AEC-Q101 qualified
- Peak wavelength:  $\lambda_p = 850$  nm
- Angle of half intensity:  $\phi = \pm 60^\circ$
- Suitable for high pulse current operation
- Floor life: 168 h, MSL 3, according to J-STD-020
- Lead (Pb)-free reflow soldering
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



## RELEASED FOR APPLICATIONS

- Infrared radiation source for operation with CMOS cameras (illumination)
- High speed IR data transmission
- Automotive sensors
- Light curtain

PRODUCT SUMMARY				
COMPONENT	$I_e$ (mW/sr) at $I_F = 100$ mA	$\phi$ (°)	$\lambda_p$ (nm)	$t_r$ (ns)
VSMY3850X01	17	$\pm 60$	850	10

### Note

- Test conditions see table “Basic Characteristics”

ORDERING INFORMATION			
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
VSMY3850X01-GS08	Tape and reel	MOQ: 7500 pcs, 1500 pcs/reel	PLCC-2
VSMY3850X01-GS18	Tape and reel	MOQ: 8000 pcs, 8000 pcs/reel	PLCC-2

### Note

- MOQ: minimum order quantity



ABSOLUTE MAXIMUM RATINGS (T <sub>amb</sub> = 25 °C, unless otherwise specified)				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		V <sub>R</sub>	5	V
Forward current		I <sub>F</sub>	100	mA
Pulse peak forward current	t <sub>p</sub> /T = 0.5, t <sub>p</sub> = 100 μs	I <sub>FM</sub>	190	mA
Surge forward current	t <sub>p</sub> = 100 μs	I <sub>FSM</sub>	1	A
Power dissipation		P <sub>V</sub>	200	mW
Junction temperature		T <sub>j</sub>	110	°C
Operating temperature range		T <sub>amb</sub>	-40 to +105	°C
Storage temperature range		T <sub>stg</sub>	-40 to +110	°C
Soldering temperature	According to Fig. 7, J-STD-020	T <sub>sd</sub>	260	°C
Thermal resistance junction-to-ambient	J-STD-051, soldered on PCB	R <sub>thJA</sub>	250	K/W

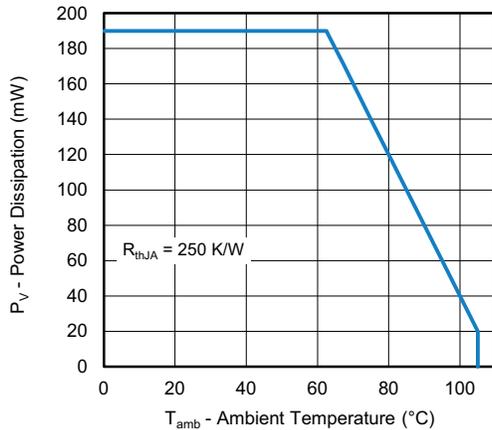


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

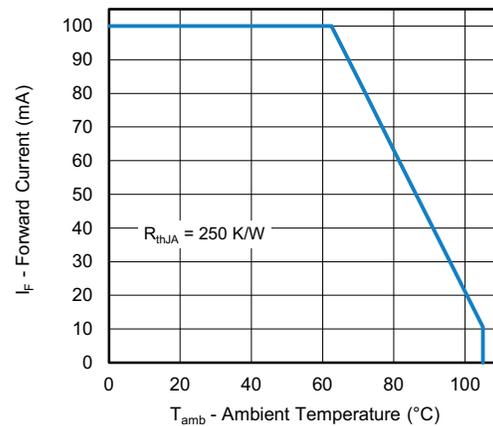


Fig. 2 - Forward Current Limit vs. Ambient Temperature

BASIC CHARACTERISTICS (T <sub>amb</sub> = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	I <sub>F</sub> = 100 mA, t <sub>p</sub> = 20 ms	V <sub>F</sub>	-	1.6	1.9	V
	I <sub>F</sub> = 1 A, t <sub>p</sub> = 100 μs	V <sub>F</sub>	-	2.8	-	V
Temperature coefficient of V <sub>F</sub>	I <sub>F</sub> = 1 mA	TK <sub>V<sub>F</sub></sub>	-	-1.5	-	mV/K
	I <sub>F</sub> = 100 mA	TK <sub>V<sub>F</sub></sub>	-	-1.2	-	mV/K
Reverse current		I <sub>R</sub>	Not designed for reverse operation			μA
Junction capacitance	V <sub>R</sub> = 0 V, f = 1 MHz, E = 0	C <sub>j</sub>	-	50	-	pF
Radiant intensity	I <sub>F</sub> = 100 mA, t <sub>p</sub> = 20 ms	I <sub>e</sub>	12	17	24	mW/sr
	I <sub>F</sub> = 1 A, t <sub>p</sub> = 100 μs	I <sub>e</sub>	-	150	-	mW/sr
Radiant power	I <sub>F</sub> = 100 mA, t <sub>p</sub> = 20 ms	φ <sub>e</sub>	-	50	-	mW
Temperature coefficient of φ <sub>e</sub>	I <sub>F</sub> = 100 mA	TKφ <sub>e</sub>	-	-0.17	-	%/K
Angle of half intensity		φ	-	± 60	-	°
Peak wavelength	I <sub>F</sub> = 100 mA	λ <sub>p</sub>	840	850	870	nm
Spectral bandwidth	I <sub>F</sub> = 100 mA	Δλ	-	30	-	nm
Temperature coefficient of λ <sub>p</sub>	I <sub>F</sub> = 100 mA	TKλ <sub>p</sub>	-	0.25	-	nm/K
Rise time	I <sub>F</sub> = 100 mA	t <sub>r</sub>	-	10	-	ns
Fall time	I <sub>F</sub> = 100 mA	t <sub>f</sub>	-	10	-	ns

**BASIC CHARACTERISTICS** ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified)

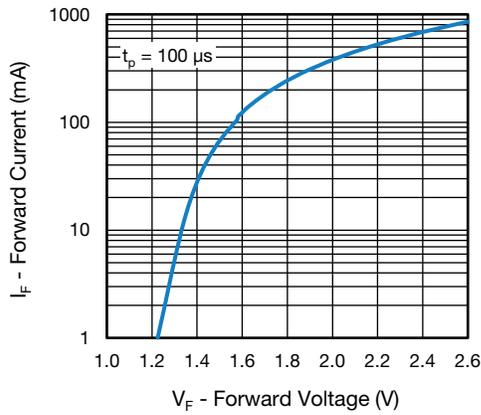


Fig. 3 - Forward Current vs. Forward Voltage

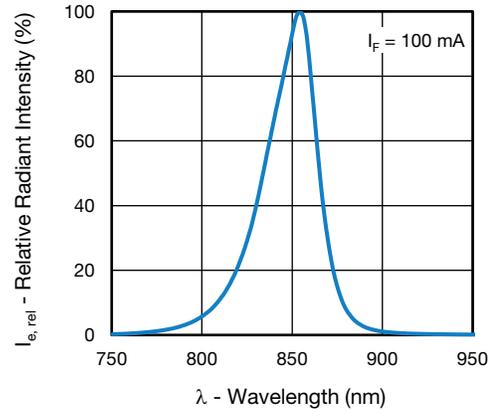


Fig. 5 - Relative Radiant Power vs. Wavelength

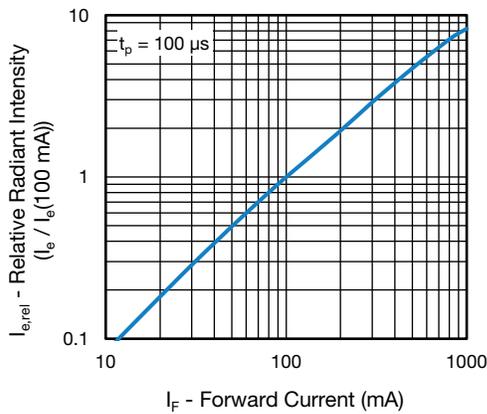


Fig. 4 - Radiant Intensity vs. Forward Current

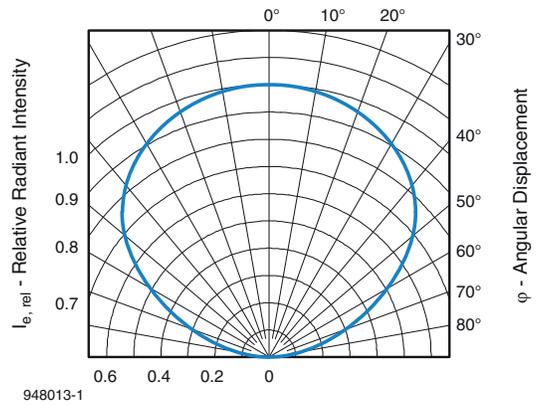
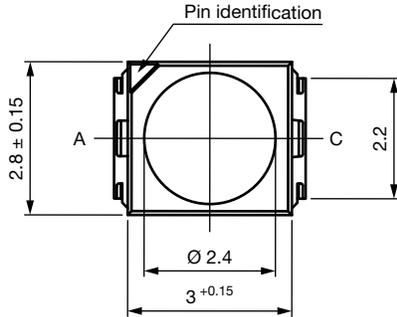
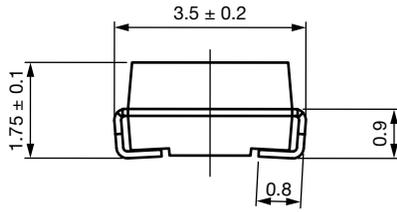


Fig. 6 - Relative Radiant Intensity vs. Angular Displacement

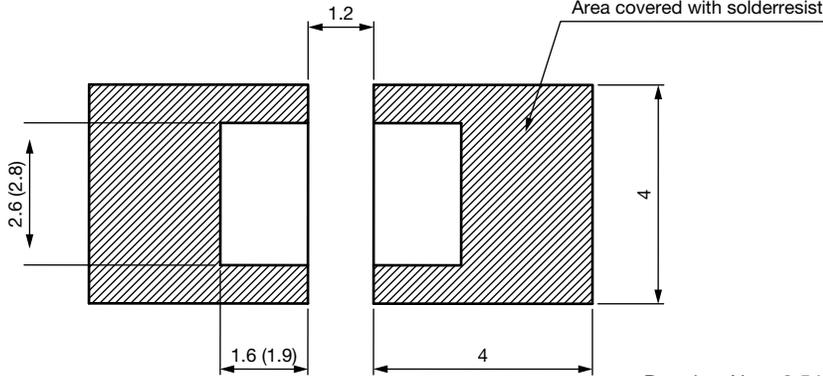


PACKAGE DIMENSIONS in millimeters



Technical drawings according to DIN specifications

Mounting pad layout



Dimensions: reflow and vapor phase (wave soldering)

Drawing-No.: 6.541-5067.02-4  
Issue: 9; 16.09.2019

SOLDER PROFILE

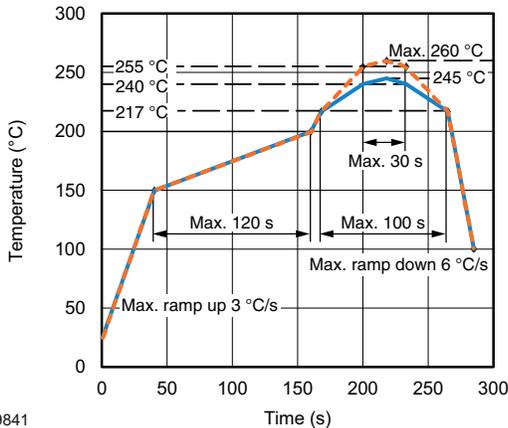


Fig. 7 - Lead (Pb)-free Reflow Solder Profile According to J-STD-020

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 168 h

Conditions: T<sub>amb</sub> < 30 °C, RH < 60 %

Moisture sensitivity level 3, according to J-STD-033D

DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 °C (+ 5 °C), RH < 5 %.

**TAPE AND REEL**

PLCC-2 components are packed in antistatic blister tape (DIN IEC (CO) 564) for automatic component insertion. Cavities of blister tape are covered with adhesive tape.

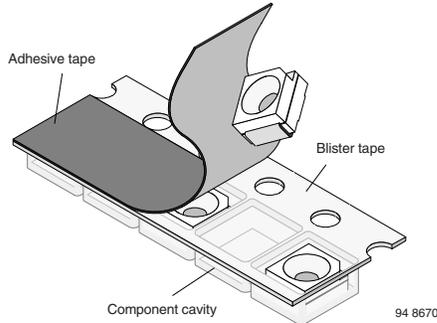


Fig. 8 - Blister Tape

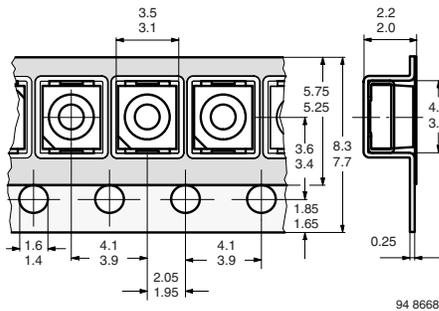


Fig. 9 - Tape Dimensions in mm for PLCC-2

**MISSING DEVICES**

A maximum of 0.5 % of the total number of components per reel may be missing, exclusively missing components at the beginning and at the end of the reel. A maximum of three consecutive components may be missing, provided this gap is followed by six consecutive components.

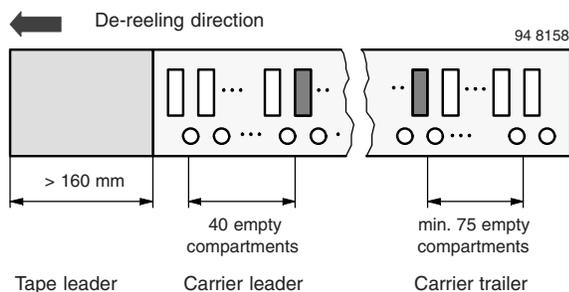


Fig. 10 - Beginning and End of Reel

The tape leader is at least 160 mm and is followed by a carrier tape leader with at least 40 empty compartments. The tape leader may include the carrier tape as long as the cover tape is not connected to the carrier tape. The least component is followed by a carrier tape trailer with a least 75 empty compartments and sealed with cover tape.

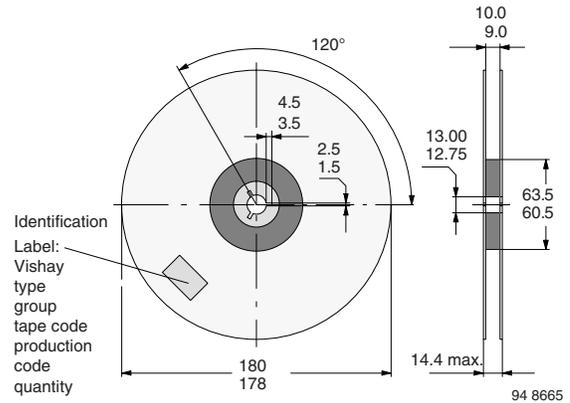


Fig. 11 - Dimensions of Reel-GS08

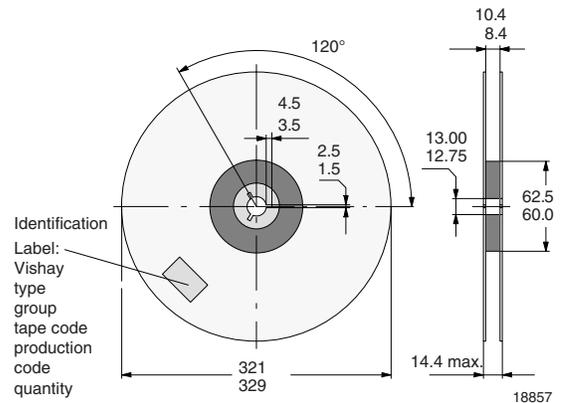


Fig. 12 - Dimensions of Reel-GS18

**COVER TAPE REMOVAL FORCE**

The removal force lies between 0.1 N and 1.0 N at a removal speed of 5 mm/s. In order to prevent components from popping out of the blisters, the cover tape must be pulled off at an angle of 180° with regard to the feed direction.



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